

PLATING BATH FOR FORMING THIN RESISTANCE LAYER, METHOD OF  
FORMATION OF RESISTANCE LAYER, CONDUCTIVE BASE WITH RESISTANCE  
LAYER, AND CIRCUIT BOARD MATERIAL WITH RESISTANCE LAYER

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ABSTRACT OF THE DISCLOSURE

A plating bath, able to form a resistance layer with a uniform thickness distribution on the roughened surface of  
10 a conductive base, including nickel ions and sulfamic acid or its salt as essential components and at least one of phosphoric acid, phosphorous acid, hypophosphorous acid, and salts of the same; a conductive base having a thin resistance layer with a stable resistance, and a resistance circuit board  
15 material using the same.